



SMT GaAs HBT MMIC DIVIDE-BY-4, DC - 8 GHz

Typical Applications

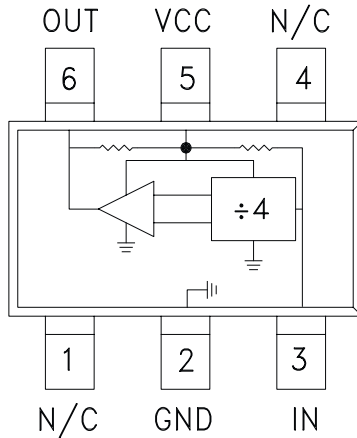
Prescaler for DC to C Band PLL Applications:

- UNII, Point-to-Point & VSAT Radios
- 802.11a & HiperLAN WLAN
- Fiber Optic
- Cellular / 3G Infrastructure

Features

- Ultra Low SSB Phase Noise: -150 dBc/Hz
- Single-Ended I/O's
- Output Power: -2 to -3.5 dBm
- Single DC Supply: +3V @ 53 mA
- 9 mm² Ultra Small Package: SOT26

Functional Diagram



General Description

The HMC433(E) is a low noise Divide-by-4 Static Divider utilizing InGaP GaAs HBT technology in ultra small surface mount SOT26 plastic packages. This device operates from DC (with a square wave input) to 8 GHz input frequency with a single +3V DC supply. Single-ended inputs and outputs reduce component count and cost. The low additive SSB phase noise of -150 dBc/Hz at 100 kHz offset helps the user maintain good system noise performance.

Electrical Specifications, $T_A = +25^\circ \text{C}$, 50 Ohm System, $V_{CC} = +3V$

Parameter	Conditions	Min.	Typ.	Max.	Units
Maximum Input Frequency		8	8.5		GHz
Minimum Input Frequency	Sine Wave Input. [1]		0.2		GHz
Input Power Range	$F_{in} = 1$ to 6 GHz	-12		+12	dBm
	$F_{in} = 6$ to 8 GHz	-3		+10	dBm
Output Power	$F_{in} = 4$ GHz	-5.0	-2.0		dBm
	$F_{in} = 8$ GHz	-6.5	-3.5		dBm
Reverse Leakage	RF Output Terminated, $F_{in} = 4$ GHz, $P_{in} = 0$ dBm		-25		dBm
SSB Phase Noise (100 kHz offset)	$P_{in} = 0$ dBm, $F_{in} = 4$ GHz		-150		dBc/Hz
Output Transition Time	$P_{in} = 0$ dBm, $F_{out} = 882$ MHz		120		ps
Supply Current (I_{CC})	$V_{CC} = +3.0V$		53	71	mA

1. Divider will operate down to DC for square-wave input signal.

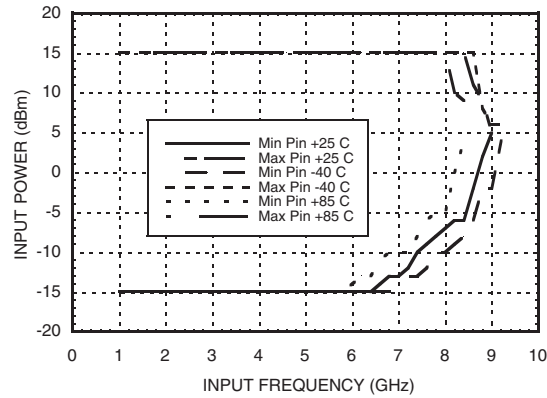


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Input Sensitivity Window, $T = 25\text{ }^{\circ}\text{C}$



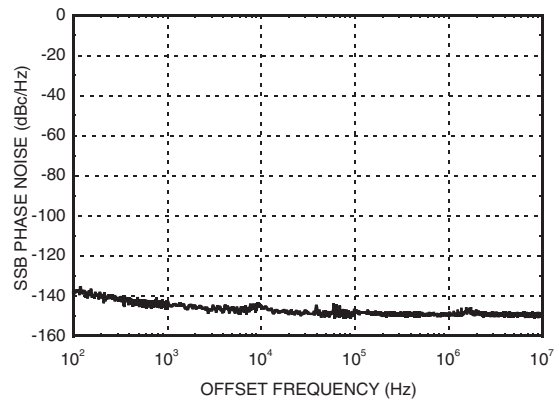
Input Sensitivity Window vs. Temperature



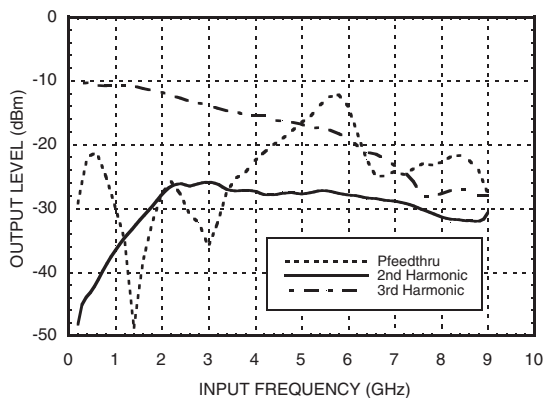
Output Power vs. Temperature



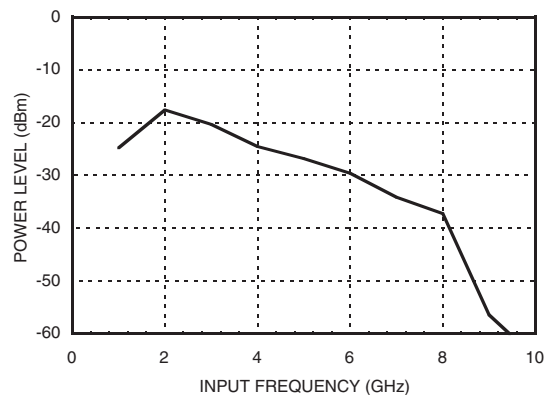
SSB Phase Noise Performance, $P_{in} = 0\text{ dBm}$, $T = 25\text{ }^{\circ}\text{C}$



Output Harmonic Content, $P_{in} = 0\text{ dBm}$, $T = 25\text{ }^{\circ}\text{C}$



Reverse Leakage, $P_{in} = 0\text{ dBm}$, $T = 25\text{ }^{\circ}\text{C}$



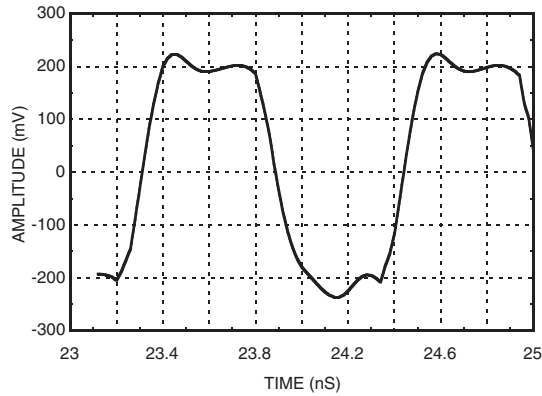
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**Output Voltage Waveform,
Pin= 0 dBm, Fout= 882 MHz, T= 25 °C**



Absolute Maximum Ratings

RF Input Power (Vcc = +3V)	15 dBm
Nominal +3V Supply to GND	-0.3V to +3.5V
Max Peak Flow Temperature	260 °C
Storage Temperature	-65 to +125 °C

Reliability Information

Junction Temperature to Maintain 1 Million Hour MTTF	135 °C
Nominal Junction Temperature (T = 85 °C)	99 °C
Thermal Resistance (Junction to GND Paddle, 3V Supply)	83 °C/W
Operating Temperature	-40 to +85 °C

DC blocking capacitors are required at RF input and RF output ports.
Choose value for lowest frequency of operation.



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Typical Supply Current vs. Vcc

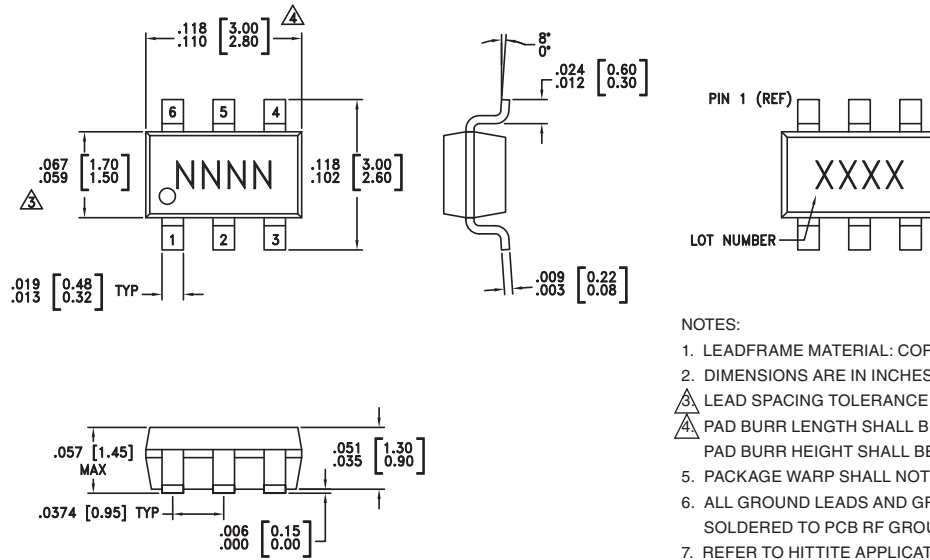
Vcc (V)	Icc (mA)
2.70	42
3.0	53
3.30	63

Note: Divider will operate over full voltage range shown above



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Outline Drawing



- NOTES:
- LEADFRAME MATERIAL: COPPER ALLOY
 - DIMENSIONS ARE IN INCHES [MILLIMETERS]
 - LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
 - PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
 - PACKAGE WARP SHALL NOT EXCEED 0.05mm.
 - ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
 - REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC433	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	H433 XXXX
HMC433E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	433E XXXX

- [1] Max peak reflow temperature of 235 °C
 [2] Max peak reflow temperature of 260 °C
 [3] 4-Digit lot number XXXX

Pin Description

Pin Number	Function	Description	Interface Schematic
1, 4	N/C	The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
2	GND	Pin must connect to RF/DC ground.	
3	IN	RF input must be DC blocked.	

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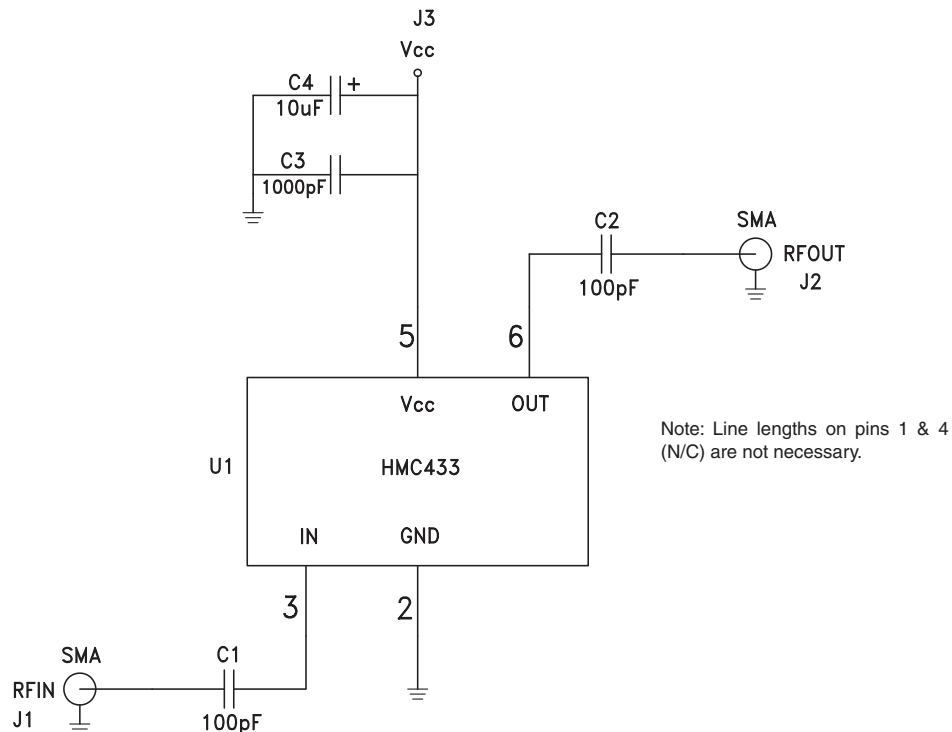


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Pin Description (Continued)

Pin Number	Function	Description	Interface Schematic
5	Vcc	Supply voltage 3V ± 0.3V.	
6	OUT	Divided output must be DC blocked.	

Application Circuit



Note:
DC blocking capacitor values (C1, C2) and DC decoupling capacitor values (C3, C4) are chosen for lowest frequency of operation.